

# AUIRGR4045D

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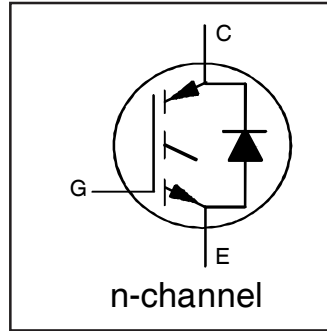
## INSULATED GATE BIPOLAR TRANSISTOR WITH ULTRAFAST SOFT RECOVERY DIODE

### Features

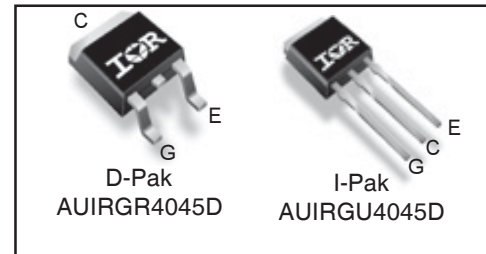
- Low  $V_{CE(on)}$  Trench IGBT Technology
- Low Switching Losses
- Maximum Junction temperature 175 °C
- 5µs SCSOA
- Square RBSOA
- 100% of the parts tested for  $I_{LM}$ ①
- Positive  $V_{CE(on)}$  Temperature Coefficient.
- Ultra Fast Soft Recovery Co-pak Diode
- Tighter Distribution of Parameters
- Lead-Free, RoHS Compliant
- Automotive Qualified\*

### Benefits

- High Efficiency in a Wide Range of Applications
- Suitable for a Wide Range of Switching Frequencies due to Low  $V_{CE(ON)}$  and Low Switching Losses
- Rugged Transient Performance for Increased Reliability
- Excellent Current Sharing in Parallel Operation
- Low EMI



$V_{CES} = 600V$   
 $I_C = 6.0A, T_C = 100^\circ C$   
 $V_{CE(on) typ.} = 1.7V$



G	C	E
Gate	Collector	Emitter

### Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature ( $T_A$ ) is 25°C, unless otherwise specified.

	Parameter	Max.	Units
$V_{CES}$	Collector-to-Emitter Breakdown Voltage	600	V
$I_C @ T_C = 25^\circ C$	Continuous Collector Current	12	A
$I_C @ T_C = 100^\circ C$	Continuous Collector Current	6.0	
$I_{CM}$	Pulsed Collector Current, $V_{GE} = 15V$	18	
$I_{LM}$	Clamped Inductive Load Current, $V_{GE} = 20V$ ①	24	
$I_F @ T_C = 25^\circ C$	Diode Continuous Forward Current	8.0	
$I_F @ T_C = 100^\circ C$	Diode Continuous Forward Current	4.0	
$I_{FM}$	Diode Maximum Forward Current ②	24	
$V_{GE}$	Continuous Gate-to-Emitter Voltage	± 20	V
	Transient Gate-to-Emitter Voltage	± 30	
$P_D @ T_C = 25^\circ$	Maximum Power Dissipation	77	W
$P_D @ T_C = 100^\circ$	Maximum Power Dissipation	39	
$T_J$	Operating Junction and	-55 to + 175	°C
$T_{STG}$	Storage Temperature Range		
	Soldering Temperature, for 10 seconds	300 (0.063 in. (1.6mm) from case)	

### Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case - IGBT ③	—	—	1.9	°C/W
$R_{\theta JC}$	Junction-to-Case - Diode ③	—	—	6.8	
$R_{\theta JA}$	Junction-to-Ambient (PCB Mount) ⑤	—	—	50	
$R_{\theta JA}$	Junction-to-Ambient	—	—	110	

\*Qualification standards can be found at <http://www.irf.com/>

## Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions	Ref.Fig
V <sub>(BR)CES</sub>	Collector-to-Emitter Breakdown Voltage	600	—	—	V	V <sub>GE</sub> = 0V, I <sub>C</sub> = 100 μA ④	CT6
ΔV <sub>(BR)CES</sub> /ΔT <sub>J</sub>	Temperature Coeff. of Breakdown Voltage	—	0.36	—	V/°C	V <sub>GE</sub> = 0V, I <sub>C</sub> = 250μA ( 25 -175 °C ) ④	
V <sub>CE(on)</sub>	Collector-to-Emitter Saturation Voltage	—	1.7	2.0	V	I <sub>C</sub> = 6.0A, V <sub>GE</sub> = 15V, T <sub>J</sub> = 25°C	5,6,7,9, 10,11
		—	2.07	—		I <sub>C</sub> = 6.0A, V <sub>GE</sub> = 15V, T <sub>J</sub> = 150°C	
		—	2.14	—		I <sub>C</sub> = 6.0A, V <sub>GE</sub> = 15V, T <sub>J</sub> = 175°C	
V <sub>GE(th)</sub>	Gate Threshold Voltage	3.5	—	6.5	V	V <sub>CE</sub> = V <sub>GE</sub> , I <sub>C</sub> = 150μA	9,10,11,12
ΔV <sub>GE(th)</sub> /ΔT <sub>J</sub>	Threshold Voltage temp. coefficient	—	-13	—	mV/°C	V <sub>CE</sub> = V <sub>GE</sub> , I <sub>C</sub> = 250μA ( 25 -175 °C )	
g <sub>fe</sub>	Forward Transconductance	—	5.8	—	S	V <sub>CE</sub> = 25V, I <sub>C</sub> = 6.0A, PW = 80μs	
I <sub>CES</sub>	Collector-to-Emitter Leakage Current	—	—	25	μA	V <sub>GE</sub> = 0V, V <sub>CE</sub> = 600V	8
		—	—	250		V <sub>GE</sub> = 0V, V <sub>CE</sub> = 600V, T <sub>J</sub> = 175°C	
V <sub>FM</sub>	Diode Forward Voltage Drop	—	1.60	2.30	V	I <sub>F</sub> = 6.0A	
		—	1.30	—		I <sub>F</sub> = 6.0A, T <sub>J</sub> = 175°C	
I <sub>GES</sub>	Gate-to-Emitter Leakage Current	—	—	±100	nA	V <sub>GE</sub> = ± 20 V	

## Switching Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions	Ref.Fig
Q <sub>g</sub>	Total Gate Charge (turn-on)	—	13	19.5	nC	I <sub>C</sub> = 6.0A	24 CT1
Q <sub>ge</sub>	Gate-to-Emitter Charge (turn-on)	—	3.1	4.65		V <sub>CC</sub> = 400V	
Q <sub>gc</sub>	Gate-to-Collector Charge (turn-on)	—	6.4	9.6		V <sub>GE</sub> = 15V	
E <sub>on</sub>	Turn-On Switching Loss	—	56	86	μJ	I <sub>C</sub> = 6.0A, V <sub>CC</sub> = 400V, V <sub>GE</sub> = 15V	CT4
E <sub>off</sub>	Turn-Off Switching Loss	—	122	143		R <sub>G</sub> = 47Ω, L=1mH, L <sub>S</sub> = 150nH, T <sub>J</sub> = 25°C	
E <sub>total</sub>	Total Switching Loss	—	178	229		Energy losses include tail and diode reverse recovery	
t <sub>d(on)</sub>	Turn-On delay time	—	27	35	ns	I <sub>C</sub> = 6.0A, V <sub>CC</sub> = 400V	CT4
t <sub>r</sub>	Rise time	—	11	15		R <sub>G</sub> = 47Ω, L=1mH, L <sub>S</sub> = 150nH	
t <sub>d(off)</sub>	Turn-Off delay time	—	75	93		T <sub>J</sub> = 25°C	
t <sub>f</sub>	Fall time	—	17	22			
E <sub>on</sub>	Turn-On Switching Loss	—	140	—		μJ	
E <sub>off</sub>	Turn-Off Switching Loss	—	189	—	R <sub>G</sub> = 47Ω, L=1mH, L <sub>S</sub> = 150nH, T <sub>J</sub> = 175°C		
E <sub>total</sub>	Total Switching Loss	—	329	—	Energy losses include tail and diode reverse recovery		
t <sub>d(on)</sub>	Turn-On delay time	—	26	—	ns	I <sub>C</sub> = 6.0A, V <sub>CC</sub> = 400V	14,16 CT4 WF1,WF2
t <sub>r</sub>	Rise time	—	12	—		R <sub>G</sub> = 47Ω, L=1mH, L <sub>S</sub> = 150nH	
t <sub>d(off)</sub>	Turn-Off delay time	—	95	—		T <sub>J</sub> = 175°C	
t <sub>f</sub>	Fall time	—	32	—			
C <sub>ies</sub>	Input Capacitance	—	350	—	pF	V <sub>GE</sub> = 0V	23
C <sub>oes</sub>	Output Capacitance	—	29	—		V <sub>CC</sub> = 30V	
C <sub>res</sub>	Reverse Transfer Capacitance	—	10	—		f = 1Mhz	
RBSOA	Reverse Bias Safe Operating Area	FULL SQUARE				T <sub>J</sub> = 175°C, I <sub>C</sub> = 24A V <sub>CC</sub> = 500V, V <sub>p</sub> = 600V R <sub>G</sub> = 100Ω, V <sub>GE</sub> = +20V to 0V	4 CT2
SCSOA	Short Circuit Safe Operating Area	—	5	—	μs	V <sub>CC</sub> = 400V, V <sub>p</sub> = 600V R <sub>G</sub> = 100Ω, V <sub>GE</sub> = +15V to 0V	22 CT3, WF4
E <sub>rec</sub>	Reverse recovery energy of the diode	—	178	—	μJ	T <sub>J</sub> = 175°C	17,18,19
t <sub>rr</sub>	Diode Reverse recovery time	—	74	—	ns	V <sub>CC</sub> = 400V, I <sub>F</sub> = 6.0A	20,21
I <sub>rr</sub>	Peak Reverse Recovery Current	—	12	—	A	V <sub>GE</sub> = 15V, R <sub>G</sub> = 47Ω, L=1mH, L <sub>S</sub> =150nH	WF3

### Notes:

- ① V<sub>CC</sub> = 80% (V<sub>CES</sub>), V<sub>GE</sub> = 15V, L = 1.0mH, R<sub>G</sub> = 47Ω.
- ② Pulse width limited by max. junction temperature.
- ③ R<sub>θ</sub> is measured at T<sub>J</sub> approximately 90°C.
- ④ Refer to AN-1086 for guidelines for measuring V<sub>(BR)CES</sub> safely.
- ⑤ When mounted on 1" square PCB (FR-4 or G-10 Material). For recommended footprint and soldering techniques refer to application note #AN-994.